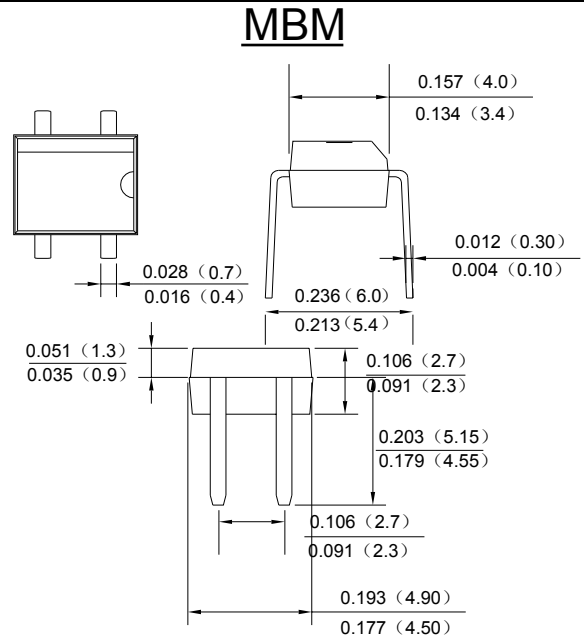


### Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-35A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

### Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



### Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.  
 Single Phase, half wave, 60Hz, resistive or inductive load.  
 For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	MB05MU	MB1MU	MB2MU	MB4MU	MB6MU	MB8MU	MB10MU	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
	V <sub>RWM</sub>								
	V <sub>DC</sub>								
RMS Reverse Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T <sub>A</sub> =40°C	I <sub>O</sub>	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	35							A
Forward Voltage per element @I <sub>F</sub> =1.0A	V <sub>FM</sub>	1.1							V
Peak Reverse Current @T <sub>A</sub> =25°C At Rated DC Blocking Voltage @T <sub>A</sub> =125°C	I <sub>R</sub>	5.0 500							uA
Typical Junction Capacitance per leg	C <sub>J</sub>	13							pF
Typical Thermal Resistance per leg (Note 2)	R <sub>θJA</sub>	70							°C/W
	R <sub>θJL</sub>	20							
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55to+150							°C

Note:1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.  
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

